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PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

November 24, 2010

Applicant: Toshihiro TAI et al

Title: PLATED RESIN MOLDED ARTICLES

Serial No.: 10/586 378

Group: 1787

Confirmation No.: 2951

Filed: July 14, 2006

Examiner: Kruer

International Application No.: PCT/JP2005/002827

International Filing Date: February 16, 2005

Atty. Docket No.: 3400.P1434US

Mail Stop Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Herewith is an amendment in the above-identified application.

[] Applicant claims small entity status. See 37 CFR 1.27.

[] The additional filing fee has been calculated as shown below:

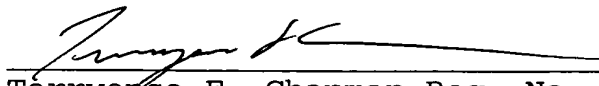
For	No. Filed	No. Extra	(X) LG Entity	RATE	() SM Entity	Fee
Total Claims	(20 - 20 = 0)		x	\$ 52.00	x	\$ 26.00
Indep. Claims	(2 - 3 = 0)		x	\$220.00	x	\$110.00
[] Multiple Dep. Claim			+	\$390.00	+	\$195.00
* * * TOTAL FILING FEE * * *						\$ 0.00

[] Pursuant to 37 CFR 1.136(a), please extend the shortened period for response by month(s). The extension fee is: \$.

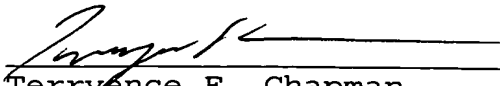
[] A Check for \$ is enclosed to cover fees.

[X] Please credit any overpayment, or charge any additional filing fee required under 37 CFR 1.16 or 1.17 by this communication, to Deposit Account No. 06-1382.

TFC/smd


Terrylene F. Chapman Reg. No. 32 549-----
CERTIFICATE OF MAILINGI hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 24, 2010.

130.10/08


Terrylene F. Chapman